

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S96	80	("3657610" "4191905" "4266156" "4405875" "4604644" "4661192" "4699682" "4734608" "4736128" "4737742" "4864470" "4993000" "5014111" "5090119" "5095240" "5120678" "5252882" "5281883" "5359494" "5390401" "5438305" "5459368" "5471722" "5504980" "5900581").PN. OR ("5969461").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/02 15:48
S97	6	("20030151135" "20040166608" "6521997" "6603210" "6838763" "6889155").PN. OR ("7145234").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/02 15:52
S98	16	("20030080437" "20030170450" "20030171456" "4339785" "5085364" "5128746" "5493259" "5529957" "5579573" "5814401" "6071371" "6202917" "6238223" "6303872" "6409070" "6521997").PN. OR ("7109592").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/02 15:54
S99	9	("5311405" "5523920" "6115262" "6156484" "6194667" "6218630").PN. OR ("6700204").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/02 16:02
S100	3	(solder adj1 mask adj1 (trench or recess or cavity)) and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/02 16:05
S101	73	MCM and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/02 16:07
S102	49	MCM and (solder adj1 mask adj1 layer) and (mold\$3 or encapsul\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/02 16:08
S103	8	(solder adj1 mask adj1 (trench or recess or cavity))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/02 16:12

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S10 5	5	(solder adj1 mask adj1 (trench or recess or cavity)) and (mold\$3 or encapsul\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/02 16:15
S10 4	2	MCM and (solder adj1 mask adj1 (trench or recess or cavity)) and (mold\$3 or encapsul\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/02 16:15
S10 6	2	(solder adj1 mask adj1 (trench or recess or cavity)) and MCM	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/02 16:16
S10 7	228	(surface adj1 mount\$3) and (solder adj1 mask adj1 layer) and (mold\$3 or encapsul\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/02 16:20
S10 8	12	((surface adj1 mount\$3) adj2 component) and (solder adj1 mask adj1 layer) and (mold\$3 or encapsul\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/02 16:21
S11 0	7	("5385869" "5612576" "5710071" "6490166" "6519844").PN. OR ("6693239").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/02 16:26
S10 9	2	("6693239").URPN.	USPAT	OR	ON	2008/02/02 16:26
L3	41	361/745	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/02 17:53
L2	534	361/751	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/02 17:53
L1	488	361/750	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/02 17:53
L9	1977	361/760.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/02 17:54
L7	620	174/521.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/02 17:54
L6	1981	174/262.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/02 17:54

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L5	2294	174/261.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/02 17:54
L4	2619	174/260.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/02 17:54
L11	2328	257/787.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/02 17:55
L10	934	257/433.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/02 17:55